Qualcomm

RF360
Europe GmbH

SAW components

SAW duplexer

Automotive telematics
LTE band 28b

Series/type:	B4427
Ordering code:	B39791B4427P810
Date:	May 26, 2017
Version:	2.0

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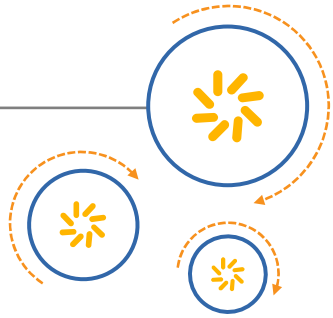
RF360 Europe GmbH, Anzinger Str. 13, München, Germany

RF360 Europe GmbH

A Qualcomm – TDK Joint Venture



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1 Application

- Low-loss SAW duplexer for band 28 systems
- Low insertion attenuation
- Low amplitude ripple
- Usable pass band 30 MHz
- Duplexer for higher part of band 28 (block b)
- Companion type is B4426 for low band 28 (block a)

2 Features

- Package size 2.0±0.1 mm × 1.6±0.1 mm
- Package height 0.45 mm (max.)
- Approximate weight 6 mg
- RoHS compatible
- Package for Surface Mount Technology (SMT)
- Ni/Au-plated terminals
- Filter surface passivated
- Electrostatic Sensitive Device (ESD)
- Moisture Sensitivity Level 2a (MSL2a)
- AEC-Q200 qualified component family (Grade 3: −40 °C to +85 °C)

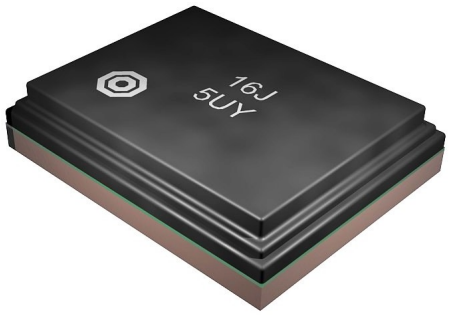

Figure 1: Picture of component with example of product marking.

3 Package

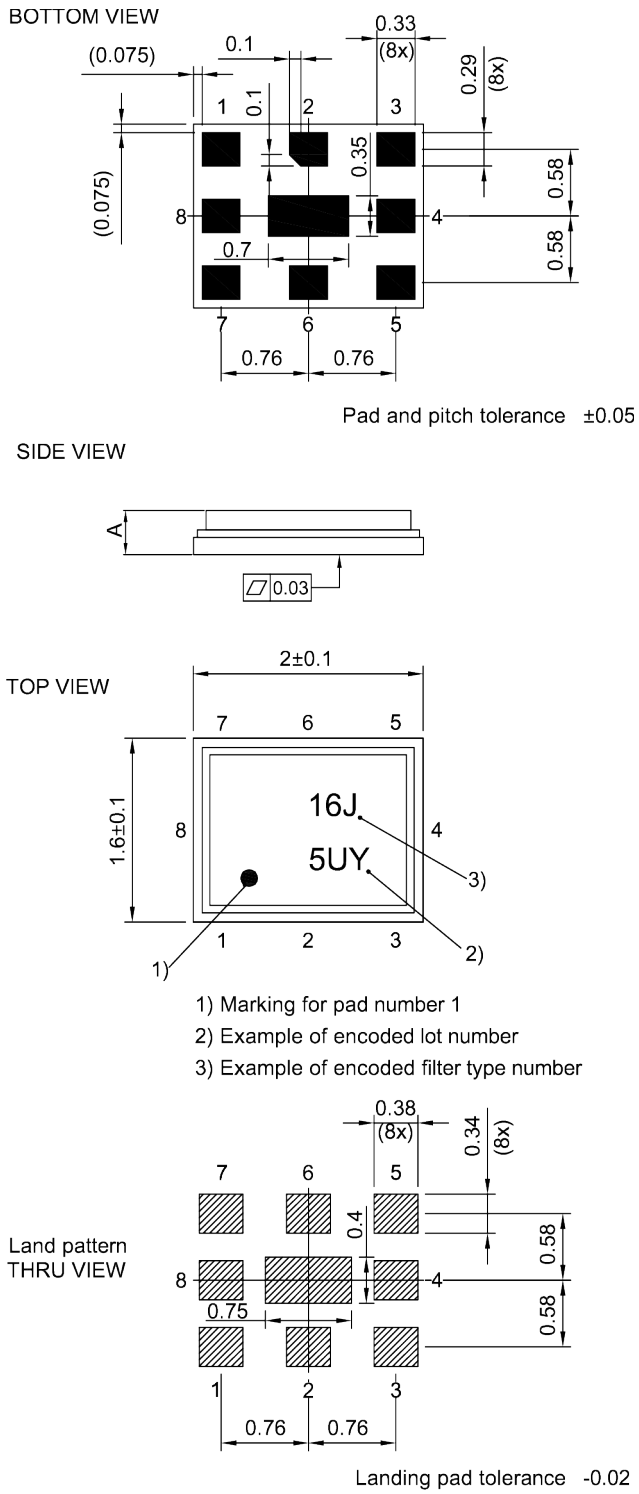

Figure 2: Drawing of package with package height A = 0.45 mm (max.). See Sec. Package information (p. 21).

4 Pin configuration

- 1 RX
- 3 TX
- 6 ANT
- 2, 4, 5, 7, 8 Ground

5 Matching circuit

■ L_{p6} = 6.0 nH ■ L_{s3} = 4.0 nH

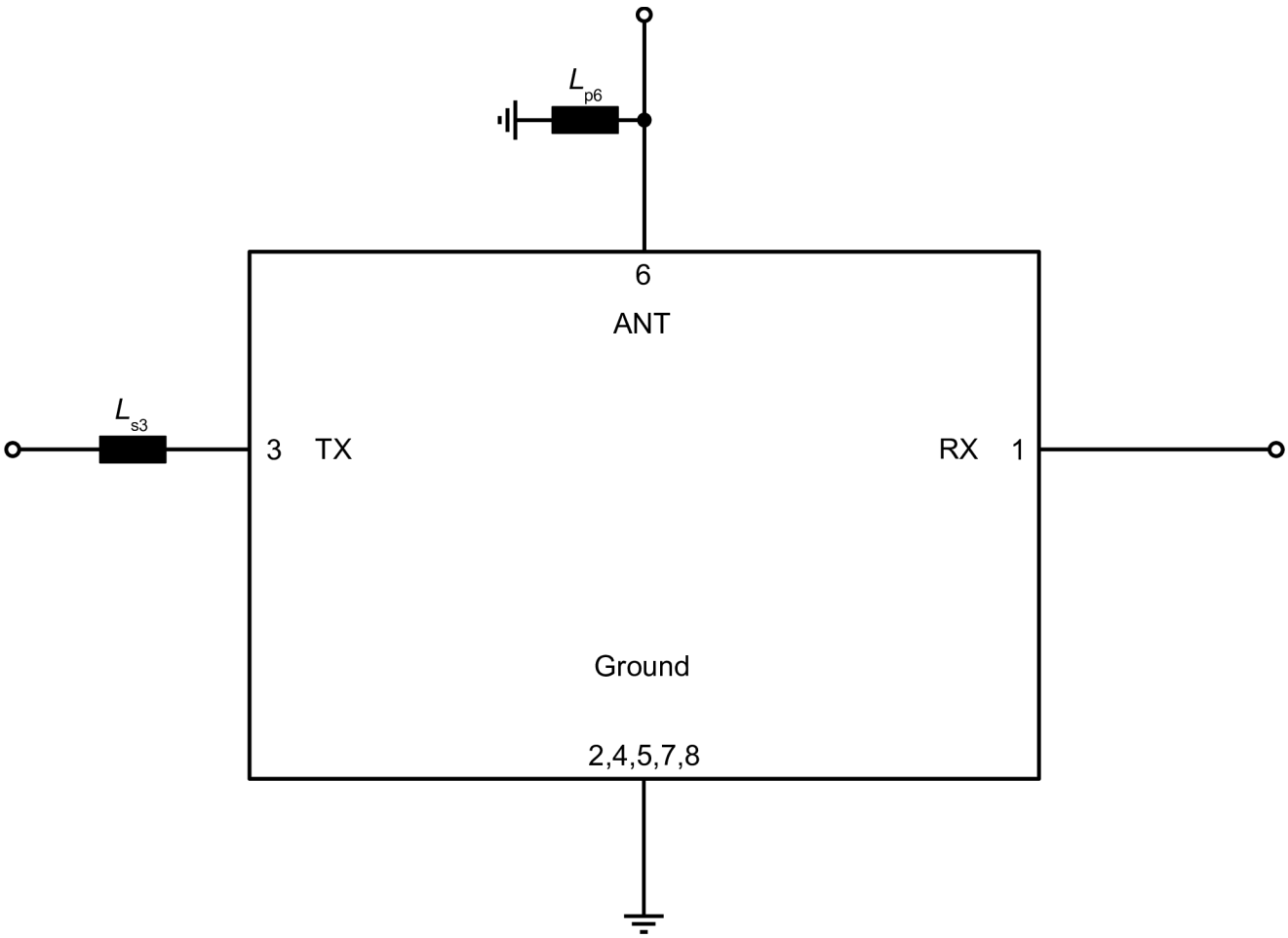

Figure 3: Schematic of matching circuit.

6 Characteristics

6.1 TX – ANT

Temperature range for specification	T_{SPEC}	= −30 °C ... +85 °C
TX terminating impedance	Z_{TX}	= 50 Ω with ser. 4.0 nH[1)]
ANT terminating impedance	Z_{ANT}	= 50 Ω with par. 6.0 nH[1)]
RX terminating impedance	Z_{RX}	= 50 Ω

Characteristics TX – ANT				**min.** for T_{SPEC}	**typ.** @ +25 °C	**max.** for T_{SPEC}	
Center frequency			f_C	—	733	—	MHz
Maximum insertion attenuation			α_{max}				
	718... 748	MHz		—	1.8	3.0	dB
	718... 748	MHz		—	1.8	3.5[2)]	dB
Amplitude ripple (p-p)			$\Delta\alpha$				
	718... 748	MHz		—	0.9	2.6	dB
Maximum VSWR			$VSWR_{max}$				
@ TX port	718... 748	MHz		—	1.8	2.1	
@ ANT port	718... 748	MHz		—	1.5	2.0	
Minimum attenuation			α_{min}				
	100... 698	MHz		30	37	—	dB
	698... 710	MHz		15	42	—	dB
	758... 773	MHz		18	34	—	dB
	773... 803	MHz		47	51	—	dB
	859... 894	MHz		30	38	—	dB
	1225... 1250	MHz		45	50	—	dB
	1436... 1606	MHz		40	42	—	dB
	1710... 2025	MHz		35	38	—	dB
	2154... 2244	MHz		32	37	—	dB
	2400... 2992	MHz		30	35	—	dB
	4900... 5950	MHz		18	24	—	dB

1) See Sec. Matching circuit (p. 6).
2) Valid for temperature T = −40 °C...+85 °C.

6.2 ANT – RX

Temperature range for specification	T_{SPEC}	= −30 °C ... +85 °C
TX terminating impedance	Z_{TX}	= 50 Ω with ser. 4.0 nH[1)]
ANT terminating impedance	Z_{ANT}	= 50 Ω with par. 6.0 nH[1)]
RX terminating impedance	Z_{RX}	= 50 Ω

Characteristics ANT – RX				**min.** for T_{SPEC}	**typ.** @ +25 °C	**max.** for T_{SPEC}	
Center frequency			f_C	—	788	—	MHz
Maximum insertion attenuation			α_{max}				
	773... 803	MHz		—	2.3	3.4	dB
	773... 803	MHz		—	2.3	3.9[2)]	dB
Amplitude ripple (p-p)			$\Delta\alpha$				
	773... 803	MHz		—	0.8	2.0	dB
Maximum VSWR			$VSWR_{max}$				
@ ANT port	773... 803	MHz		—	1.5	2.0	
@ RX port	773... 803	MHz		—	1.9	2.2	
Minimum attenuation			α_{min}				
	100... 718	MHz		50	63	—	dB
	718... 748	MHz		50	64	—	dB
	820... 830	MHz		26	43	—	dB
	830... 4300	MHz		40	48	—	dB
	4300... 6000	MHz		30	39	—	dB

1) See Sec. Matching circuit (p. 6).
2) Valid for temperature T = −40 °C...+85 °C.

6.3 TX – RX

Temperature range for specification	T_{SPEC}	= −30 °C ... +85 °C
TX terminating impedance	Z_{TX}	= 50 Ω with ser. 4.0 nH[1)]
ANT terminating impedance	Z_{ANT}	= 50 Ω with par. 6.0 nH[1)]
RX terminating impedance	Z_{RX}	= 50 Ω

Characteristics TX – RX			**min.** for T_{SPEC}	**typ.** @ +25 °C	**max.** for T_{SPEC}	
Minimum isolation		α_{min}				
	718... 748	MHz	60	63	—	dB
	773... 803	MHz	54	60	—	dB

1) See Sec. Matching circuit (p. 6).

7 Maximum ratings

Operable temperature	T_{OP} = −40 °C ... +85 °C	
Storage temperature	T_{STG} [1] = −40 °C ... +85 °C	
DC voltage	$\|V_{DC}\|$ [2] = 0 V	
Input power @ TX port: 718 ... 748 MHz	P_{IN} = 29 dBm	Continuous wave for 5000 h @ 50 °C.

1) Not valid for packaging material. Storage temperature for packaging material is −25 °C to +40 °C.
2) In case of applied DC voltage blocking capacitors are mandatory.

8 Transmission coefficients

8.1 TX – ANT

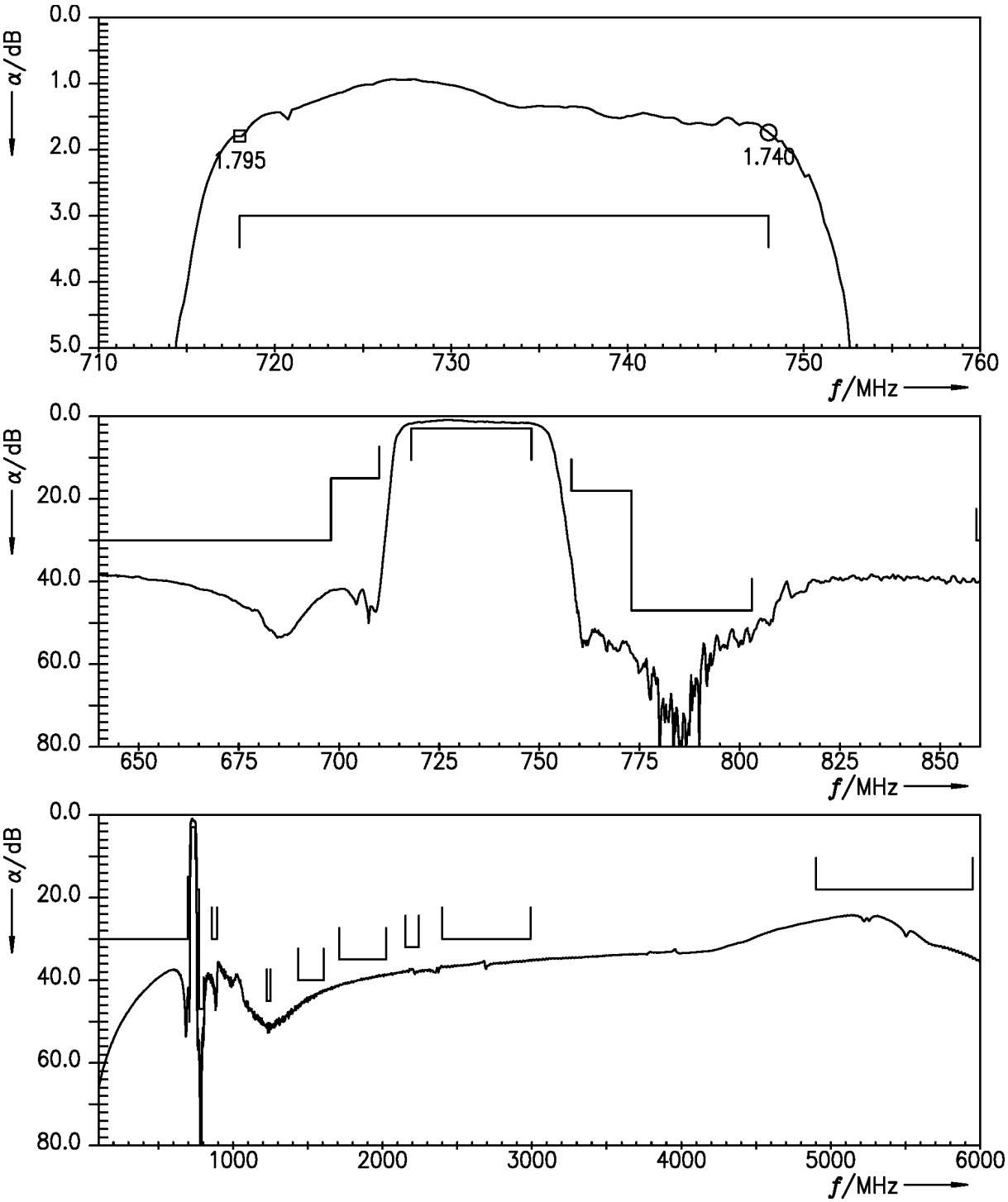

Figure 4: Attenuation TX – ANT.

8.2 ANT – RX

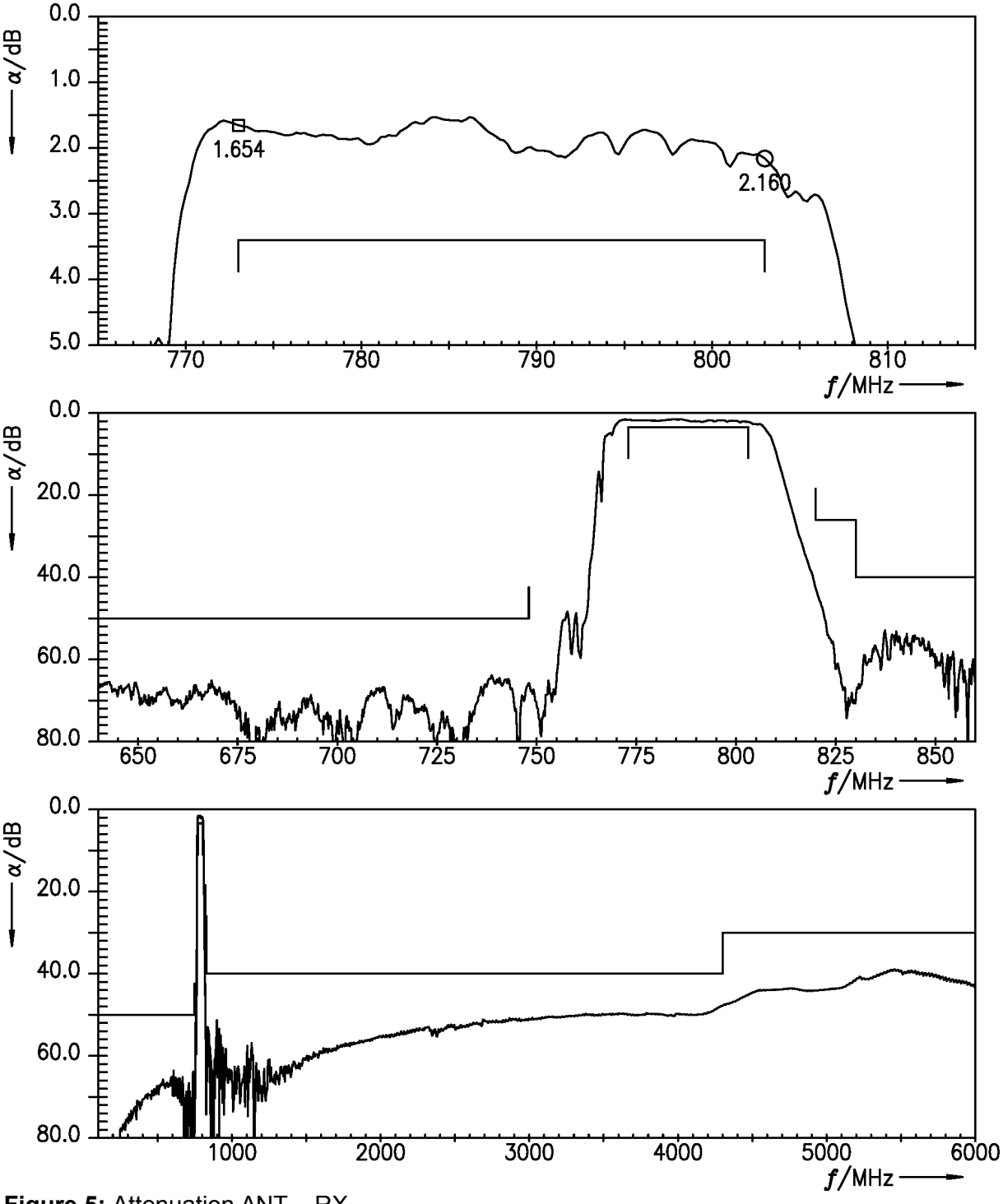

Figure 5: Attenuation ANT – RX.

8.3 TX – RX

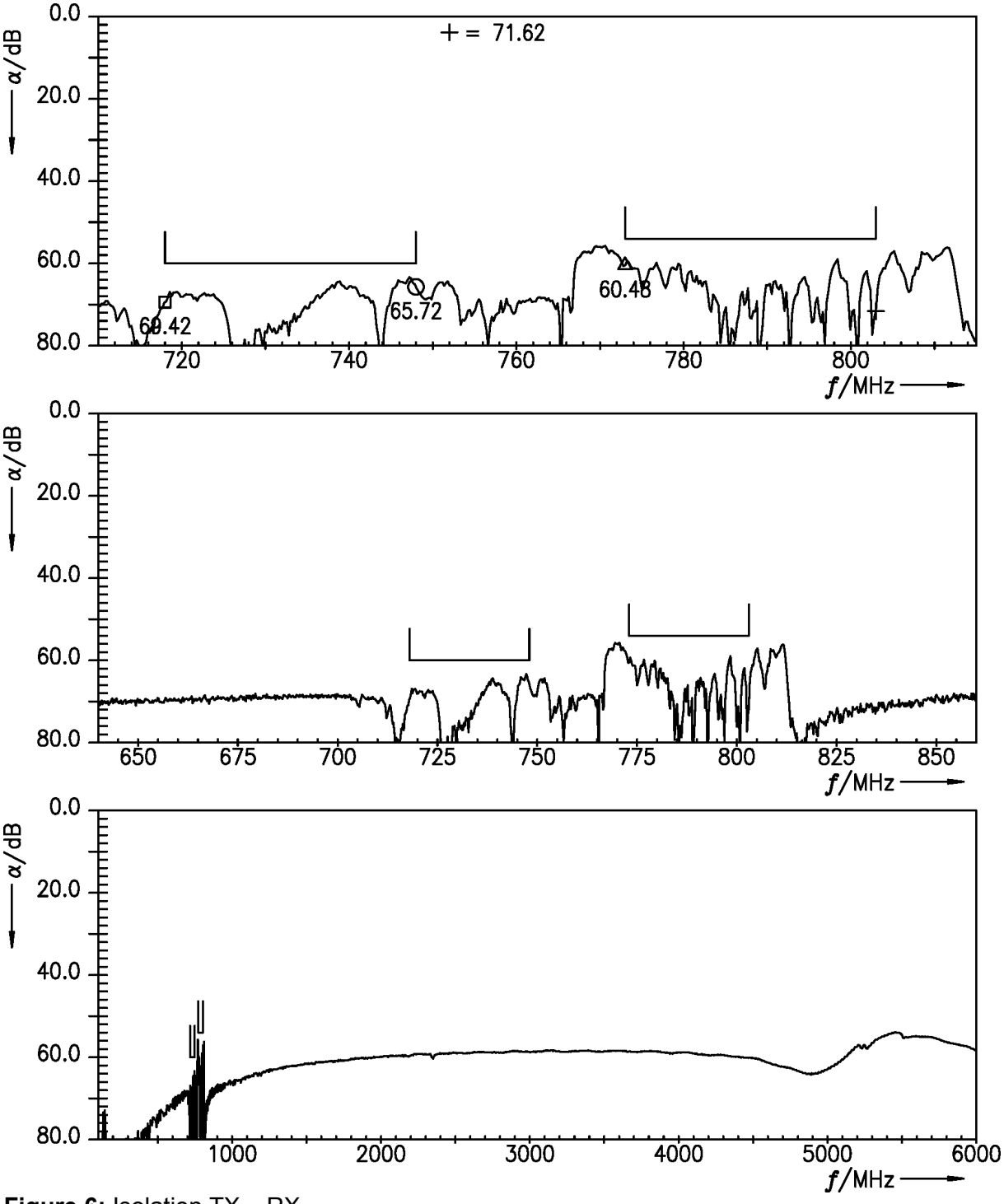

Figure 6: Isolation TX – RX.

9 Reflection coefficients

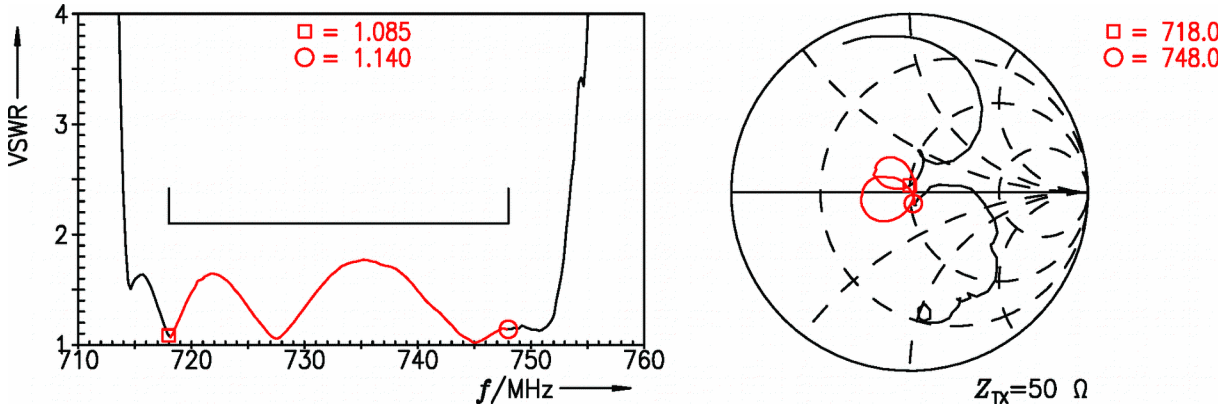

Figure 7: Reflection coefficient at TX port.

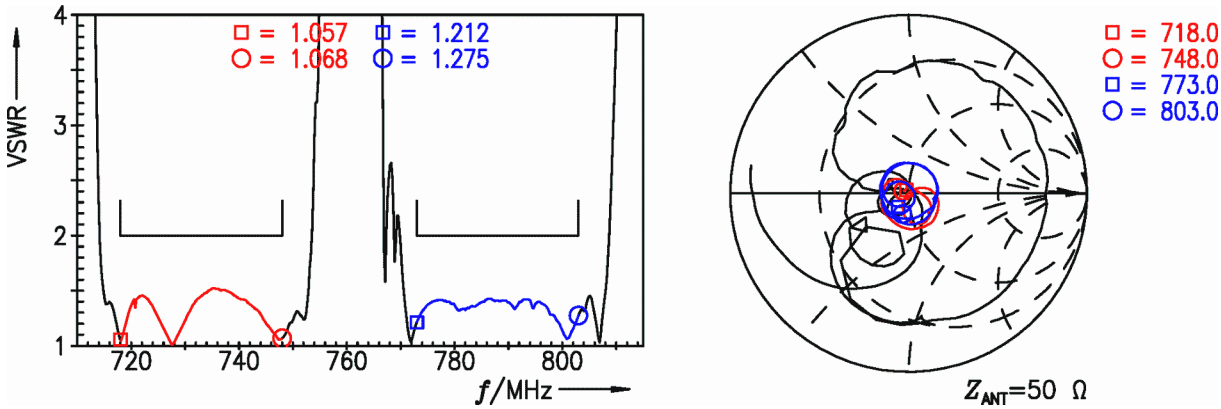

Figure 8: Reflection coefficient at ANT port.

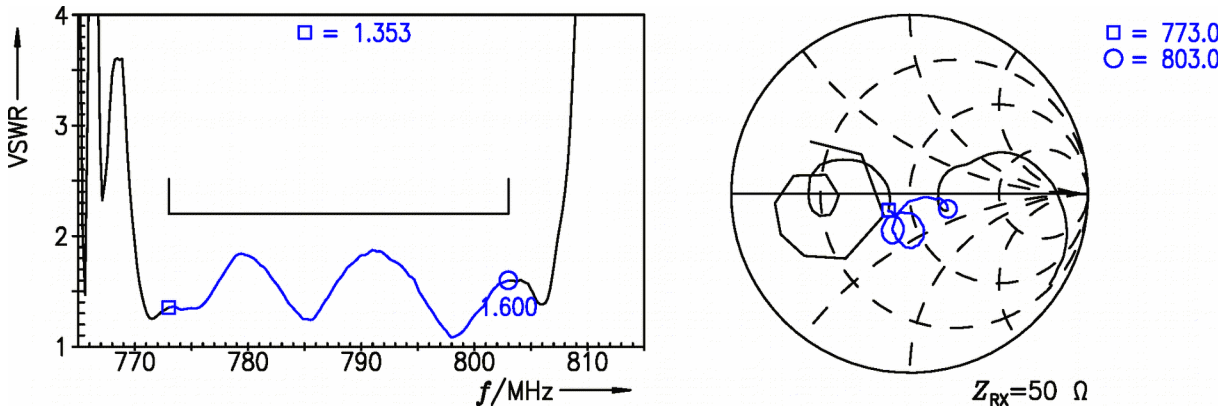

Figure 9: Reflection coefficient at RX port.

10 Packing material

10.1 Tape

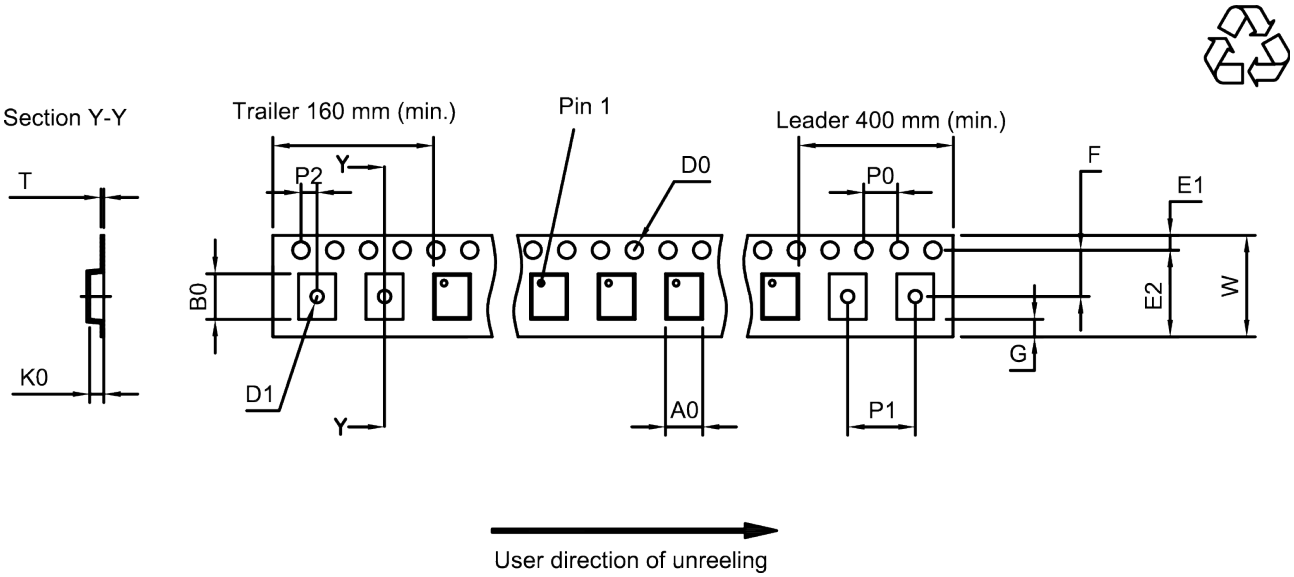

Figure 10: Drawing of tape (first-angle projection) with tape dimensions according to Table 1.

A_0	$1.8_{\pm 0.05}$ mm
B_0	$2.25_{\pm 0.05}$ mm
D_0	$1.5^{+0.1/-0}$ mm
D_1	1.0 mm (min.)
E_1	$1.75_{\pm 0.1}$ mm

E_2	6.25 mm (min.)
F	$3.5_{\pm 0.05}$ mm
G	0.75 mm (min.)
K_0	$0.6_{\pm 0.05}$ mm
P_0	$4.0_{\pm 0.1}$ mm

P_1	$4.0_{\pm 0.1}$ mm
P_2	$2.0_{\pm 0.05}$ mm
T	$0.25_{\pm 0.03}$ mm
W	$8.0^{+0.3/-0.1}$ mm

Table 1: Tape dimensions.

10.2 Reel with diameter of 180 mm

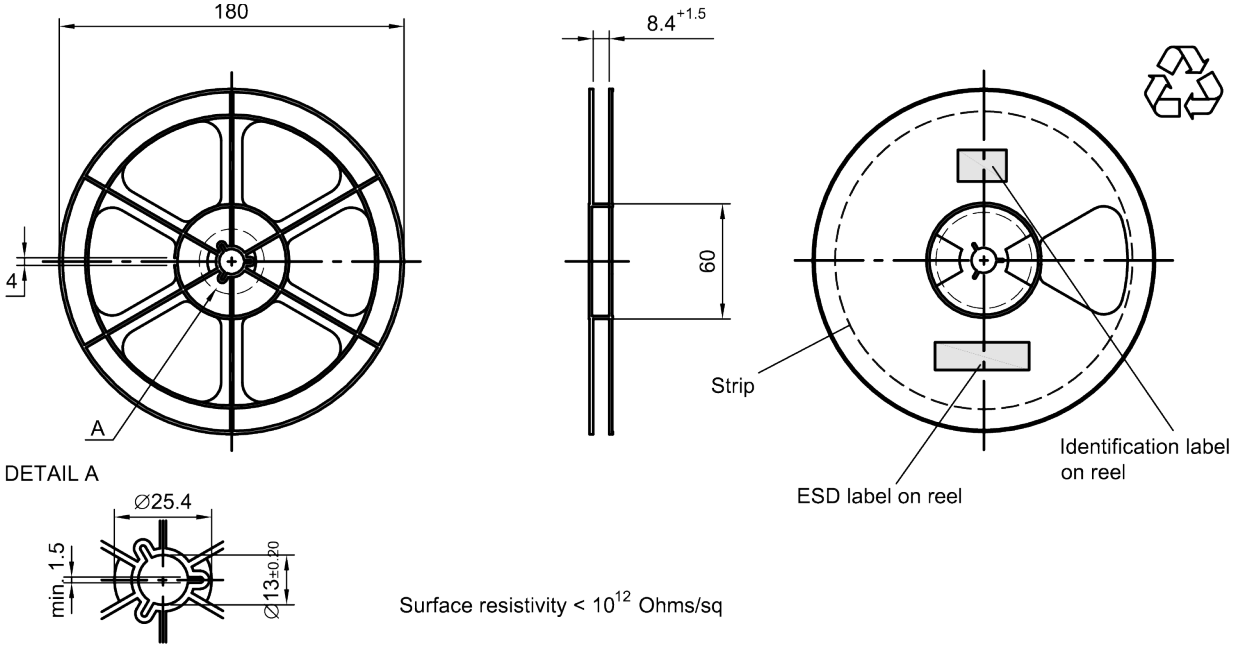

Figure 11: Drawing of reel (first-angle projection) with diameter of 180 mm.

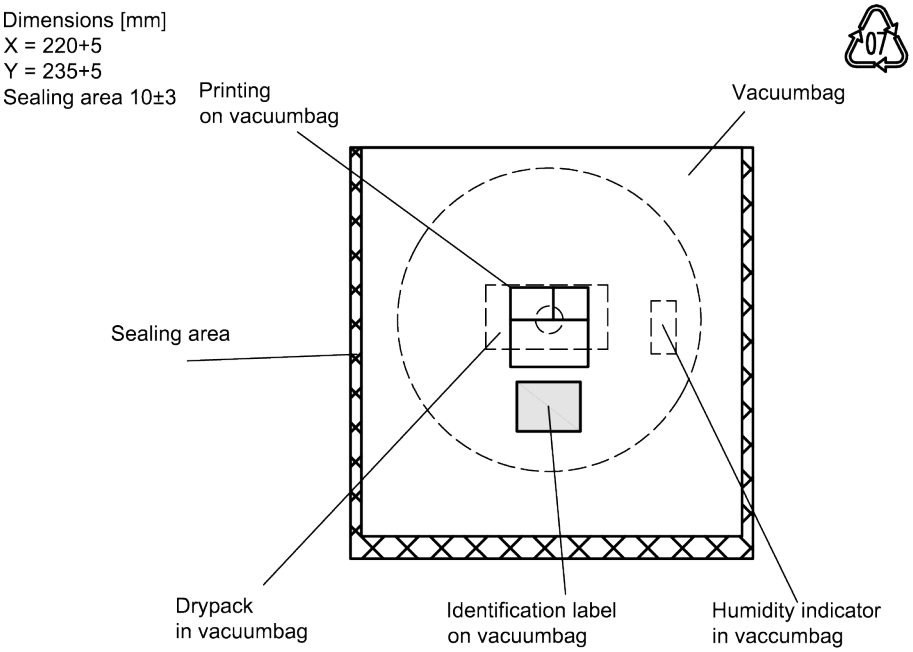

Figure 12: Drawing of moisture barrier bag (MBB) for reel with diameter of 180 mm.

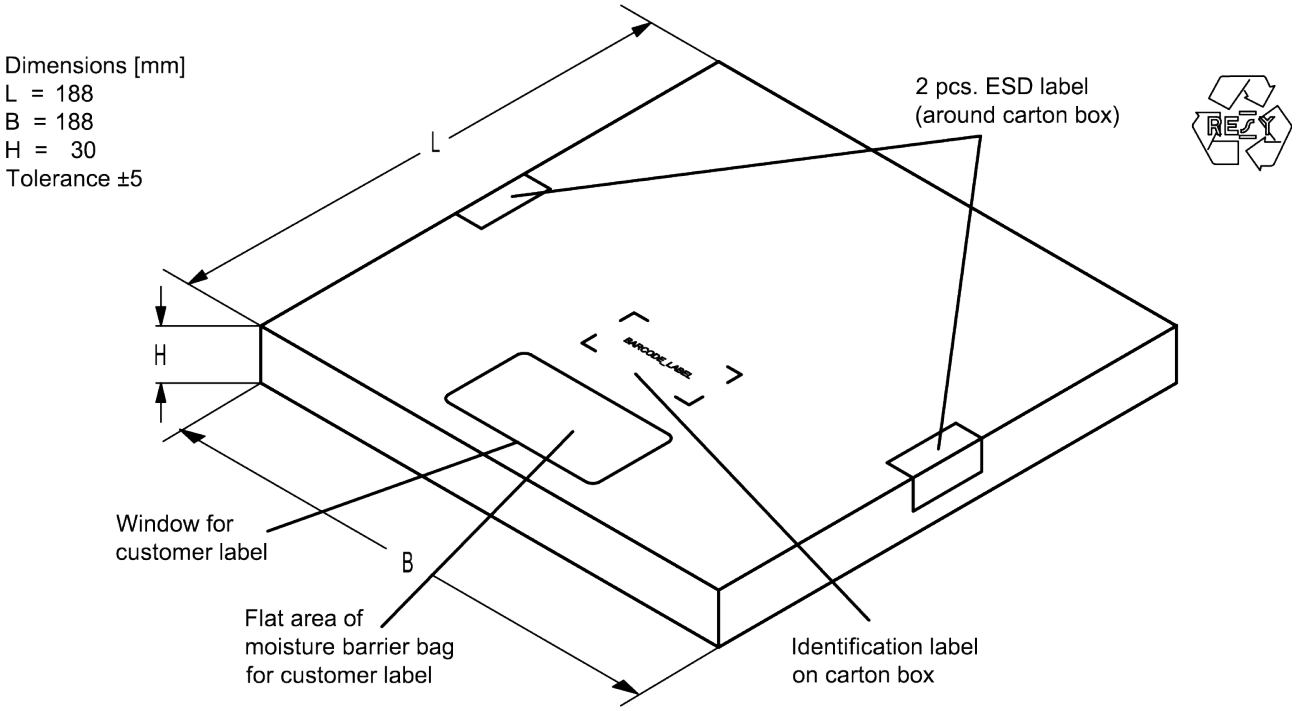

Figure 13: Drawing of folding box for reel with diameter of 180 mm.

11 Marking

Products are marked with product type number and lot number encoded according to Table 2:

- Type number:

  The 4 digit type number of the ordering code, e.g., B3xxxxB**1234**xxxx,
  is encoded by a special BASE32 code into a 3 digit marking.

  Example of decoding type number marking on device in decimal code.
  16J **=>** **1234**
  1 x 32^2 + **6** x 32^1 + **18 (=J)** x 32^0 **=** **1234**
  The BASE32 code for product type B4427 is 4AB.

- Lot number:

  The last 5 digits of the lot number, e.g., **12345**,
  are encoded based on a special BASE47 code into a 3 digit marking.

  Example of decoding lot number marking on device in decimal code.
  5UY **=>** **12345**
  5 x 47^2 + **27 (=U)** x 47^1 + **31 (=Y)** x 47^0 **=** **12345**

Adopted BASE32 code for type number			
Decimal value	Base32 code	Decimal value	Base32 code
0	0	16	G
1	1	17	H
2	2	18	J
3	3	19	K
4	4	20	M
5	5	21	N
6	6	22	P
7	7	23	Q
8	8	24	R
9	9	25	S
10	A	26	T
11	B	27	V
12	C	28	W
13	D	29	X
14	E	30	Y
15	F	31	Z

Adopted BASE47 code for lot number			
Decimal value	Base47 code	Decimal value	Base47 code
0	0	24	R
1	1	25	S
2	2	26	T
3	3	27	U
4	4	28	V
5	5	29	W
6	6	30	X
7	7	31	Y
8	8	32	Z
9	9	33	b
10	A	34	d
11	B	35	f
12	C	36	h
13	D	37	n
14	E	38	r
15	F	39	t
16	G	40	v
17	H	41	\
18	J	42	?
19	K	43	{
20	L	44	}
21	M	45	<
22	N	46	>
23	P		

Table 2: Lists for encoding and decoding of marking.

12 Soldering profile

The recommended soldering process is in accordance with IEC 60068-2-58 – 3rd edit and IPC/JEDEC J-STD-020B.

ramp rate	≤ 3 K/s
preheat	125 °C to 220 °C, 150 s to 210 s, 0.4 K/s to 1.0 K/s
T > 220 °C	30 s to 70 s
T > 230 °C	min. 10 s
T > 245 °C	max. 20 s
T ≥ 255 °C	–
peak temperature T_{peak}	250 °C +0/-5 °C
wetting temperature T_{min}	230 °C +5/-0 °C for 10 s ± 1 s
cooling rate	≤ 3 K/s
soldering temperature T	measured at solder pads

Table 3: Characteristics of recommended soldering profile for lead-free solder (Sn95.5Ag3.8Cu0.7).

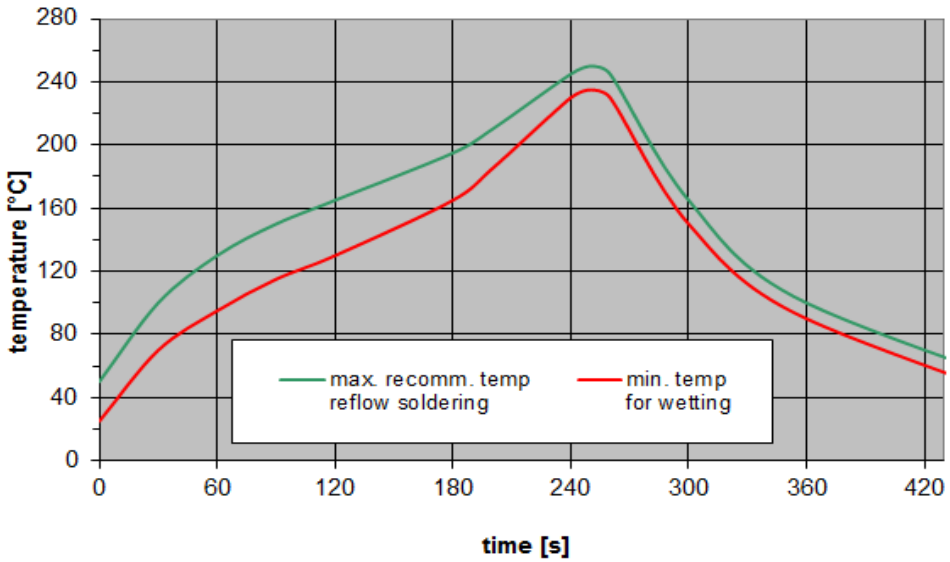

Figure 14: Recommended reflow profile for convection and infrared soldering – lead-free solder.

13 Annotations

13.1 Matching coils

See TDK inductor pdf-catalog http://www.tdk.co.jp/tefe02/coil.htm#aname1 and Data Library for circuit simulation http://www.tdk.co.jp/etvcl/index.htm.

13.2 RoHS compatibility

ROHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011, on the restriction of the use of certain hazardous substances in electrical and electronic equipment ("Directive") with due regard to the application of exemptions as per Annex III of the Directive in certain cases.

13.3 Scattering parameters (S-parameters)

The pin/port assignment is available in the headers of the S-parameter files. Please contact your local RF360 sales office.

14 Cautions and warnings

14.1 Display of ordering codes for RF360 products

The ordering code for one and the same product can be represented differently in data sheets, data books, other publications and the website of RF360, or in order-related documents such as shipping notes, order confirmations and product labels. The varying representations of the ordering codes are due to different processes employed and do not affect the specifications of the respective products. Detailed information can be found on the Internet under www.rf360jv.com/orderingcodes.

14.2 Material information

Due to technical requirements components may contain dangerous substances. For information on the type in question please also contact one of our sales offices.

For information on recycling of tapes and reels please contact one of our sales offices.

14.3 Moldability

Before using in overmolding environment, please contact your local RF360 sales office.

14.4 Package information

Landing area

The printed circuit board (PCB) land pattern (landing area) shown is based on RF360 internal development and empirical data and illustrated for example purposes, only. As customers' SMD assembly processes may have a plenty of variants and influence factors which are not under control or knowledge of RF360, additional careful process development on customer side is necessary and strongly recommended in order to achieve best soldering results tailored to the particular customer needs.

Dimensions

Unless otherwise specified all dimensions are understood using unit millimeter (mm).

Dimensions do not include burrs.

Projection method

Unless otherwise specified first-angle projection is applied.

Important notes

The following applies to all products named in this publication:

1. Some parts of this publication contain **statements about the suitability of our products for certain areas of application**. These statements are based on our knowledge of typical requirements that are often placed on our products in the areas of application concerned. We nevertheless expressly point out **that such statements cannot be regarded as binding statements about the suitability of our products for a particular customer application.** As a rule, RF360 Europe GmbH and its affiliates are either unfamiliar with individual customer applications or less familiar with them than the customers themselves. For these reasons, it is always ultimately incumbent on the customer to check and decide whether an RF360 product with the properties described in the product specification is suitable for use in a particular customer application.
2. We also point out that **in individual cases, a malfunction of electronic components or failure before the end of their usual service life cannot be completely ruled out in the current state of the art, even if they are operated as specified.** In customer applications requiring a very high level of operational safety and especially in customer applications in which the malfunction or failure of an electronic component could endanger human life or health (e.g. in accident prevention or life-saving systems), it must therefore be ensured by means of suitable design of the customer application or other action taken by the customer (e.g. installation of protective circuitry or redundancy) that no injury or damage is sustained by third parties in the event of malfunction or failure of an electronic component.
3. **The warnings, cautions and product-specific notes must be observed.**
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